



Form 1449 (Modified) Information Disclosure Statement By Applicant (Use Several Sheets if Necessary)	Atty Docket No. NOVL085/NVLS-2875	Application No.: 10/785,235
	Applicant: Wang et al.	
	Filing Date February 23, 2004	Group 2812 2823

U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
FLT ↓	A1	6,867,086 B1	03.2005	Chen et al.			
	A2	6,903,004	06.2005	Spencer et al.			
	A3	6,232,658 B1	05.2001	Catabay et al.			
	A4	6,171,661	01.2001	Zheng et al.			
	A5	2002/0016085	02.2002	Huang et al.			
	A6	6,455,417	09.2002	Bao et al.			
	A7	7,018,918	03.2006	Kloster et al.			
	A8	6,849,549	02.2005	Chiou et al.			

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
FLT ↓ V	C1	U.S. Office Action mailed May 31, 2006, from U.S Application No. 10/941,502 [Atty Dkt No. NOVLP107/NVLS-2932].
	C2	U.S. Office Action mailed May 31, 2006, from U.S Application No. 10/849,568 [Atty Dkt No. NOVLP083/NVLS-2867].
	C3	U.S. Office Action mailed May 2, 2006, from U.S Application No. 11/050,621 [Atty Dkt No. NOVLP100/NVLS-2956].
	C4	U.S. Office Action mailed June 15, 2006, from U.S Application No. 10/800,409 [Atty Dkt No. NOVLP098/NVLS-2907].
	C5	Kelman et al., "Method for Reducing Stress in Porous Dielectric Films", U.S. Application No. 11/369,311, filed March 6, 2006 (Atty Dkt: NOVLP154/NVLS-3121)
	C6	U.S. Office Action mailed May 2, 2006, from U.S Application No. 10/295,965.
	C7	U.S. Office Action mailed August 9, 2005, from U.S Application No. 10/295,965.
	C8	U.S. Office Action mailed June 14, 2006, from U.S Application No. 10/789,103 [Atty Dkt No. NOVLP094/NVLS-2919].
	C9	U.S. Office Action mailed June 28, 2006, from U.S Application No. 10/825,888 [Atty Dkt No. NOVLP088/NVLS-2882].
Examiner	/Fernando L. Toledo/	
Date Considered	09/27/2006	

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered.
Include copy of this form with next communication to applicant.